

SOT1182-1

plastic thermal enhanced extremely thin quad flat package;
no leads; 16 terminals

8 February 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HXQFN16
Package type industry code	HXQFN16
Package style descriptive code	HXQFN (thermal enhanced extremely thin quad flatpack; no leads)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	- - -
JEITA package outline code	- - -
Mounting method type	S (surface mount)
Issue date	16-9-2010

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	1.9	-	2	2.1	mm
E	package width	1.9	-	2	2.1	mm
A	seated height	[tbd]	-	[tbd]	0.5	mm
e	nominal pitch	-	-	0.4	-	mm
n ₂	actual quantity of termination	-	-	16	-	

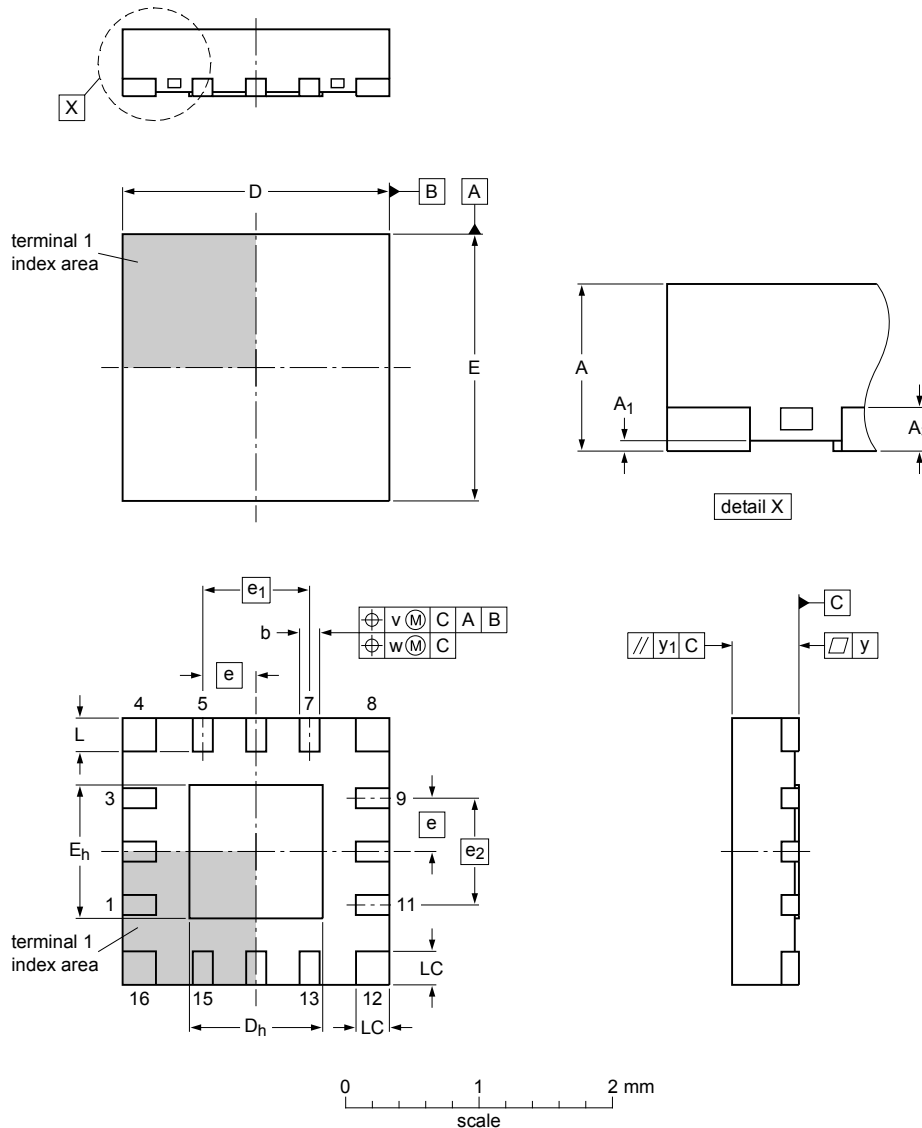


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2. Package outline

HXQFN16: plastic thermal enhanced extremely thin quad flat package; no leads; 16 terminals; body 2 x 2 x 0.5 mm

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Dimensions

Unit	A	A ₁	A ₃	b	D	D _h	E	E _h	e	e ₁	e ₂	L	LC	v	w	y	y ₁
max	0.5	0.05		0.20	2.1	1.1	2.1	1.1				0.30	0.30				
nom			0.127	0.15	2.0	1.0	2.0	1.0	0.4	0.8	0.8	0.25	0.25	0.1	0.05	0.05	0.1
min		0.00		0.10	1.9	0.9	1.9	0.9				0.20	0.20				

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Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
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Fig. 1. Package outline HXQFN16 (SOT1182-1)

3. Legal information

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